Silicon PNP Epitaxial

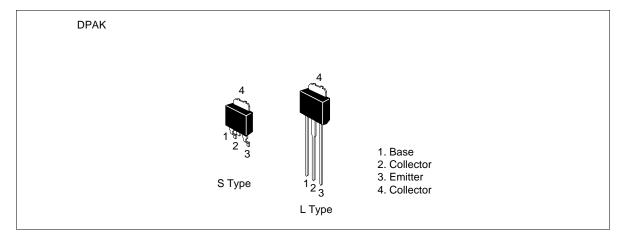
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ADE-208-877 (Z) 1st. Edition Sep. 2000

Application

Low frequency power amplifier complementary Pair with 2SD2123(L)/(S)

Outline





Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{\scriptscriptstyle \sf CBO}$	-180	V
Collector to emitter voltage	V _{CEO} -160		V
Emitter to base voltage	V_{EBO}	- 5	V
Collector current	I _c	-1.5	А
Collector peak current	I _{C(peak)}	-3	А
Collector power dissipation	P _c *1	18	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. Value at $T_c = 25$ °C.

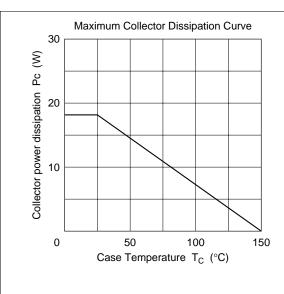
Electrical Characteristics ($Ta = 25^{\circ}C$)

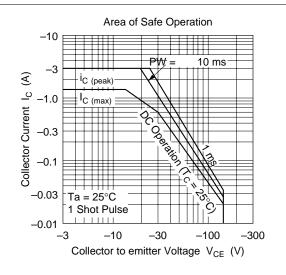
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-180	_	_	V	$I_{c} = -1 \text{ mA}, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-160	_	_	V	$I_{c} = -10 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	- 5	_	_	V	$I_{E} = -1 \text{ mA}, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-10	μΑ	$V_{CB} = -160 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE1} *1	60	_	200		$V_{CE} = -5 \text{ V}, I_{C} = -150 \text{ mA}^{*2}$
	h _{FE2}	30	_	_	_	$V_{CE} = -5 \text{ V}, I_{C} = -500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-1	V	$I_{\rm C} = -500 \text{ mA}, I_{\rm B} = -50 \text{ mA}$
Base to emitter voltage	V_{BE}	_	_	-1.5	V	$V_{CE} = -5 \text{ V}, I_{C} = -150 \text{ mA}$
Gain bandwidth product	f _T	_	240	_	MHz	$V_{CE} = -5 \text{ V}, I_{C} = -150 \text{ mA}$
Collector output capacitance	Cob	_	25	_	pF	$V_{CB} = -10 \text{ A}, I_{E} = 0, f = 1 \text{ MHz}$

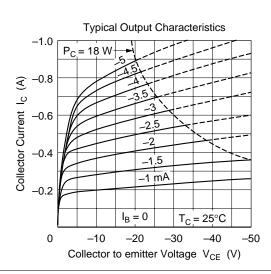
Notes: 1. The 2SB1409(L)/(S) is grouped by h_{FE_1} as follows.

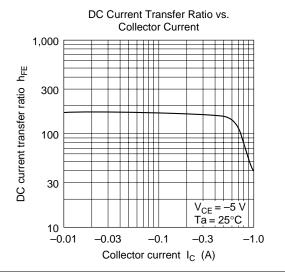
В	C
60 to 120	100 to 200

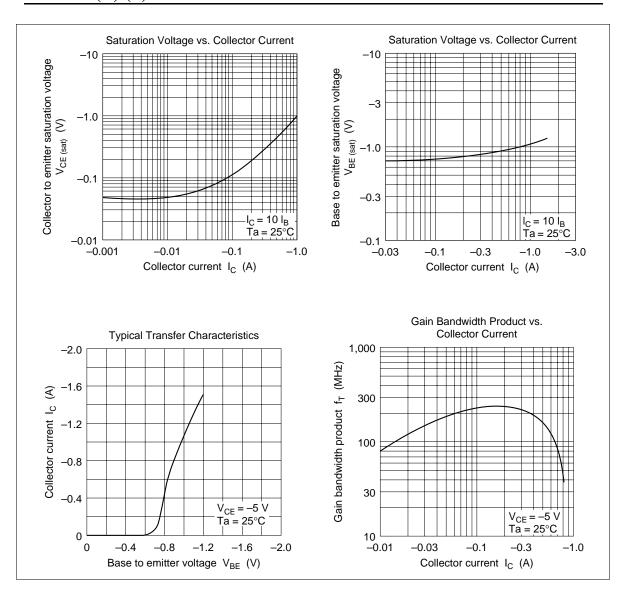
2. Pulse test.

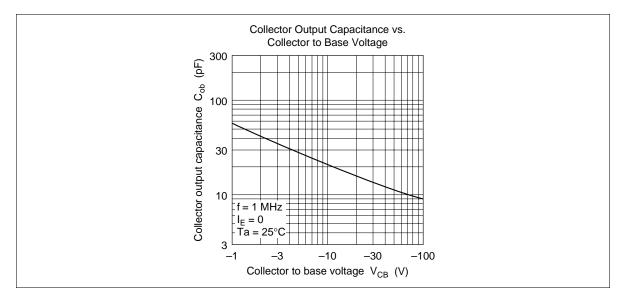




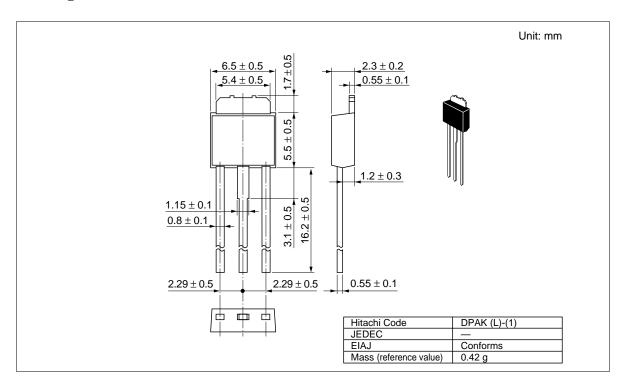


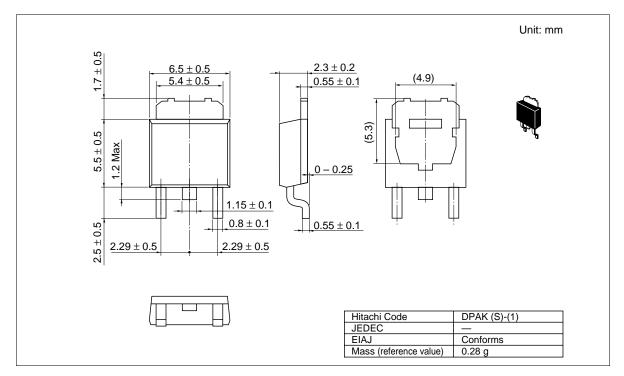






Package Dimensions





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